



**ABSOLUTE MAXIMUM RATINGS**

Symbol	Parameter	Test conditions	Value	Unit
$V_S$	Supply Voltage	$V_{SA} = V_{SB} = V_S$	60	V
$V_{OD}$	Differential Voltage between: $V_{SA}$ , $OUT_1$ , $OUT_2$ , $SENSE_A$ and $V_{SB}$ , $OUT_3$ , $SENSE_B$	$V_{SA} = V_{SB} = V_S = 60V$ ; $V_{SENSE_A} = V_{SENSE_B} = GND$	60	V
$V_{BOOT}$	Bootstrap Peak Voltage	$V_{SA} = V_{SB} = V_S$	$V_S + 10$	V
$V_{IN}$ , $V_{EN}$	Logic Inputs Voltage Range		-0.3 to 7	V
$V_{REF}$	Voltage Range at pin $V_{REF}$		-0.3 to 7	V
$V_{RCOFF}$	Voltage Range at pin $RCOFF$		-0.3 to 7	V
$V_{RCPULSE}$	Voltage Range at pin $RCPULSE$		-0.3 to 7	V
$V_{SENSE}$	Voltage Range at pins $SENSE_A$ and $SENSE_B$		-1 to 4	V
$I_{S(peak)}$	Pulsed Supply Current (for each $V_{SA}$ and $V_{SB}$ pin)	$V_{SA} = V_{SB} = V_S$ ; $T_{PULSE} < 1ms$	7.1	A
$I_S$	DC Supply Current (for each $V_{SA}$ and $V_{SB}$ pin)	$V_{SA} = V_{SB} = V_S$	2.8	A
$T_{stg}$ , $T_{OP}$	Storage and Operating Temperature Range		-40 to 150	°C

**RECOMMENDED OPERATING CONDITION**

Symbol	Parameter	Test Conditions	MIN	MAX	Unit
$V_S$	Supply Voltage	$V_{SA} = V_{SB} = V_S$	12	52	V
$V_{OD}$	Differential Voltage between: $V_{SA}$ , $OUT_1$ , $OUT_2$ , $SENSE_A$ and $V_{SB}$ , $OUT_3$ , $SENSE_B$	$V_{SA} = V_{SB} = V_S$ ; $V_{SENSE_A} = V_{SENSE_B}$		52	V
$V_{REF}$	Voltage Range at pin $V_{REF}$		-0.1	5	V
$V_{SENSE}$	Voltage Range at pins $SENSE_A$ and $SENSE_B$	(pulsed $t_W < t_{rr}$ ) (DC)	-6 -1	6 1	V V
$I_{OUT}$	DC Output Current	$V_{SA} = V_{SB} = V_S$		2.8	A
$T_J$	Operating Junction Temperature		-25	125	°C
$f_{SW}$	Switching Frequency			100	KHz

## THERMAL DATA

Symbol	Description	PDIP24	SO24	PowerSO36	Unit
$R_{th(j-pins)}$	Maximum Thermal Resistance Junction-Pins	18	14		°C/W
$R_{th(j-case)}$	Maximum Thermal Resistance Junction-Case			1	°C/W
$R_{th(j-amb)1}$	Maximum Thermal Resistance Junction-Ambient <sup>(1)</sup>	43	51	-	°C/W
$R_{th(j-amb)1}$	Maximum Thermal Resistance Junction-Ambient <sup>(2)</sup>	-	-	35	°C/W
$R_{th(j-amb)1}$	Maximum Thermal Resistance Junction-Ambient <sup>(3)</sup>	-	-	15	°C/W
$R_{th(j-amb)2}$	Maximum Thermal Resistance Junction-Ambient <sup>(4)</sup>	58	77	62	°C/W

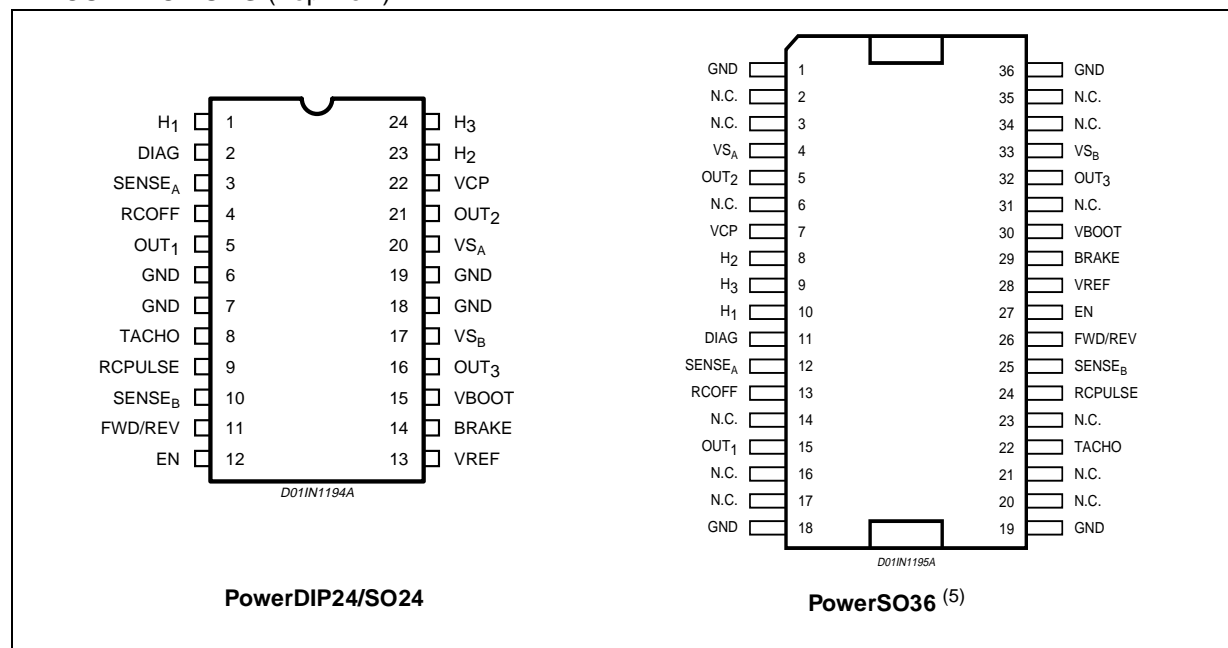
(1) Mounted on a multi-layer FR4 PCB with a dissipating copper surface on the bottom side of 6 cm<sup>2</sup> (with a thickness of 35 μm).

(2) Mounted on a multi-layer FR4 PCB with a dissipating copper surface on the top side of 6 cm<sup>2</sup> (with a thickness of 35 μm).

(3) Mounted on a multi-layer FR4 PCB with a dissipating copper surface on the top side of 6 cm<sup>2</sup> (with a thickness of 35 μm), 16 via holes and a ground layer.

(4) Mounted on a multi-layer FR4 PCB without any heat-sinking surface on the board.

## PIN CONNECTIONS (Top view)



(5) The slug is internally connected to pins 1, 18, 19 and 36 (GND pins).

## PIN DESCRIPTION

PACKAGE		Name	Type	Function
SO24/ PowerDIP24	PowerSO36			
PIN #	PIN #			
1	10	H <sub>1</sub>	Sensor Input	Single Ended Hall Effect Sensor Input 1.
2	11	DIAG	Open Drain Output	Overcurrent Detection and Thermal Protection pin. An internal open drain transistor pulls to GND when an overcurrent on one of the High Side MOSFETs is detected or during Thermal Protection.
3	12	SENSE <sub>A</sub>	Power Supply	Half Bridge 1 and Half Bridge 2 Source Pin. This pin must be connected together with pin SENSE <sub>B</sub> to Power Ground through a sensing power resistor.
4	13	RCOFF	RC Pin	RC Network Pin. A parallel RC network connected between this pin and ground sets the Current Controller OFF-Time.
5	15	OUT <sub>1</sub>	Power Output	Output 1
6, 7, 18, 19	1, 18, 19, 36	GND	GND	Ground terminals. On PowerDIP24 and SO24 packages, these pins are also used for heat dissipation toward the PCB. On PowerSO36 package the slug is connected on these pins.
8	22	TACHO	Open Drain Output	Frequency-to-Voltage open drain output. Every pulse from pin H <sub>1</sub> is shaped as a fixed and adjustable length pulse.
9	24	RCPULSE	RC Pin	RC Network Pin. A parallel RC network connected between this pin and ground sets the duration of the Monostable Pulse used for the Frequency-to-Voltage converter.
10	25	SENSE <sub>B</sub>	Power Supply	Half Bridge 3 Source Pin. This pin must be connected together with pin SENSE <sub>A</sub> to Power Ground through a sensing power resistor. At this pin also the Inverting Input of the Sense Comparator is connected.
11	26	FWD/REV	Logic Input	Selects the direction of the rotation. HIGH logic level sets Forward Operation, whereas LOW logic level sets Reverse Operation. If not used, it has to be connected to GND or +5V..
12	27	EN	Logic Input	Chip Enable. LOW logic level switches OFF all Power MOSFETs. If not used, it has to be connected to +5V.
13	28	VREF	Logic Input	Current Controller Reference Voltage. Do not leave this pin open or connect to GND.
14	29	BRAKE	Logic Input	Brake Input pin. LOW logic level switches ON all High Side Power MOSFETs, implementing the Brake Function. If not used, it has to be connected to +5V.
15	30	VBOOT	Supply Voltage	Bootstrap Voltage needed for driving the upper Power MOSFETs.
16	32	OUT <sub>3</sub>	Power Output	Output 3.
17	33	VS <sub>B</sub>	Power Supply	Half Bridge 3 Power Supply Voltage. It must be connected to the supply voltage together with pin VS <sub>A</sub> .

## PIN DESCRIPTION (continued)

PACKAGE		Name	Type	Function
SO24/ PowerDIP24	PowerSO36			
PIN #	PIN #			
20	4	VS <sub>A</sub>	Power Supply	Half Bridge 1 and Half Bridge 2 Power Supply Voltage. It must be connected to the supply voltage together with pin VS <sub>B</sub> .
21	5	OUT <sub>2</sub>	Power Output	Output 2.
22	7	VCP	Output	Charge Pump Oscillator Output.
23	8	H <sub>2</sub>	Sensor Input	Single Ended Hall Effect Sensor Input 2.
24	9	H <sub>3</sub>	Sensor Input	Single Ended Hall Effect Sensor Input 3.

## ELECTRICAL CHARACTERISTICS

(V<sub>S</sub> = 48V , T<sub>amb</sub> = 25 °C , unless otherwise specified)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
V <sub>Sth(ON)</sub>	Turn ON threshold		6.6	7	7.4	V
V <sub>Sth(OFF)</sub>	Turn OFF threshold		5.6	6	6.4	V
I <sub>S</sub>	Quiescent Supply Current	All Bridges OFF; T <sub>j</sub> = -25 to 125°C <sup>(6)</sup>		5	10	mA
T <sub>J(OFF)</sub>	Thermal Shutdown Temperature			165		°C

## Output DMOS Transistors

R <sub>DSON</sub>	High-Side Switch ON Resistance	T <sub>j</sub> = 25 °C		0.34	0.4	Ω
		T <sub>j</sub> = 125 °C <sup>(6)</sup>		0.53	0.59	Ω
	Low-Side Switch ON Resistance	T <sub>j</sub> = 25 °C		0.28	0.34	Ω
		T <sub>j</sub> = 125 °C <sup>(6)</sup>		0.47	0.53	Ω
I <sub>DSS</sub>	Leakage Current	EN = Low; OUT = V <sub>CC</sub>			2	mA
		EN = Low; OUT = GND	-0.15			mA

## Source Drain Diodes

V <sub>SD</sub>	Forward ON Voltage	I <sub>SD</sub> = 2.8A, EN = LOW		1.15	1.3	V
t <sub>rr</sub>	Reverse Recovery Time	I <sub>f</sub> = 2.8A		300		ns
t <sub>fr</sub>	Forward Recovery Time			200		ns

## Logic Input (H1, H2, H3, EN, FWD/REV, BRAKE)

V <sub>IL</sub>	Low level logic input voltage		-0.3		0.8	V
V <sub>IH</sub>	High level logic input voltage		2		7	V
I <sub>IL</sub>	Low level logic input current	GND Logic Input Voltage	-10			μA
I <sub>IH</sub>	High level logic input current	7V Logic Input Voltage			10	μA
V <sub>th(ON)</sub>	Turn-ON Input Threshold			1.8	2.0	V
V <sub>th(OFF)</sub>	Turn-OFF Input Threshold		0.8	1.3		V
V <sub>thHYS</sub>	Input Thresholds Hysteresys		0.25	0.5		V

**ELECTRICAL CHARACTERISTICS** (continued)(V<sub>S</sub> = 48V, T<sub>amb</sub> = 25 °C, unless otherwise specified)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
<b>Switching Characteristics</b>						
t <sub>D(on)EN</sub>	Enable to out turn-ON delay time <sup>(7)</sup>	I <sub>LOAD</sub> = 2.8 A, Resistive Load	110	250	400	ns
t <sub>D(off)EN</sub>	Enable to out turn-OFF delay time <sup>(7)</sup>	I <sub>LOAD</sub> = 2.8 A, Resistive Load	300	550	800	ns
t <sub>D(on)IN</sub>	Other Logic Inputs to Output Turn-ON delay Time	I <sub>LOAD</sub> = 2.8 A, Resistive Load			2	μs
t <sub>D(off)IN</sub>	Other Logic Inputs to out Turn-OFF delay Time	I <sub>LOAD</sub> = 2.8 A, Resistive Load			2	μs
t <sub>RISE</sub>	Output Rise Time <sup>(7)</sup>	I <sub>LOAD</sub> = 2.8 A, Resistive Load	40		250	ns
t <sub>FALL</sub>	Output Fall Time <sup>(7)</sup>	I <sub>LOAD</sub> = 2.8 A, Resistive Load	40		250	ns
t <sub>DT</sub>	Dead Time		0.5	1		μs
f <sub>CP</sub>	Charge Pump Frequency	T <sub>J</sub> = -25 to 125°C <sup>(6)</sup>		0.6	1	MHz

**PWM Comparator and Monostable**

I <sub>RCOFF</sub>	Source current at pin RCOFF	V <sub>RCOFF</sub> = 2.5 V	3.5	5.5		mA
V <sub>OFFSET</sub>	Offset Voltage on Sense Comparator	V <sub>ref</sub> = 0.5 V		±5		mV
t <sub>prop</sub>	Turn OFF Propagation delay <sup>(8)</sup>	V <sub>ref</sub> = 0.5 V		500		ns
t <sub>blank</sub>	Internal Blanking Time on Sense Comparator			1		μs
t <sub>ON(min)</sub>	Minimum on Time			1.5	2	μs
t <sub>OFF</sub>	PWM Recirculation Time	R <sub>OFF</sub> = 20kΩ ; C <sub>OFF</sub> = 1nF		13		μs
		R <sub>OFF</sub> = 100kΩ ; C <sub>OFF</sub> = 1nF		61		μs
I <sub>BIAS</sub>	Input Bias Current at pin VREF				10	μA

**Tacho Monostable**

I <sub>RCPULSE</sub>	Source Current at pin RCPULSE	V <sub>RCPULSE</sub> = 2.5V	3.5	5.5		mA
t <sub>PULSE</sub>	Monostable of Time	R <sub>PUL</sub> = 20kΩ ; C <sub>PUL</sub> = 1nF		12		μs
		R <sub>PUL</sub> = 100kΩ ; C <sub>PUL</sub> = 1nF		60		μs
R <sub>TACHO</sub>	Open Drain ON Resistance			40	60	Ω

**Over Current Detection & Protection**

I <sub>SOVER</sub>	Supply Overcurrent Protection Threshold	T <sub>J</sub> = -25 to 125°C <sup>(6)</sup>	4.0	5.6	7.1	A
R <sub>OPDR</sub>	Open Drain ON Resistance	I <sub>DIAG</sub> = 4mA		40	60	Ω
I <sub>OH</sub>	OCD high level leakage current	V <sub>DIAG</sub> = 5V		1		μA
t <sub>OCD(ON)</sub>	OCD Turn-ON Delay Time <sup>(9)</sup>	I <sub>DIAG</sub> = 4mA; C <sub>DIAG</sub> < 100pF		200		ns
t <sub>OCD(OFF)</sub>	OCD Turn-OFF Delay Time <sup>(9)</sup>	I <sub>DIAG</sub> = 4mA; C <sub>DIAG</sub> < 100pF		100		ns

(6) Tested at 25°C in a restricted range and guaranteed by characterization.

(7) See Fig. 1.

(8) Measured applying a voltage of 1V to pin SENSE and a voltage drop from 2V to 0V to pin VREF.

(9) See Fig. 2.

Figure 1. Switching Characteristic Definition

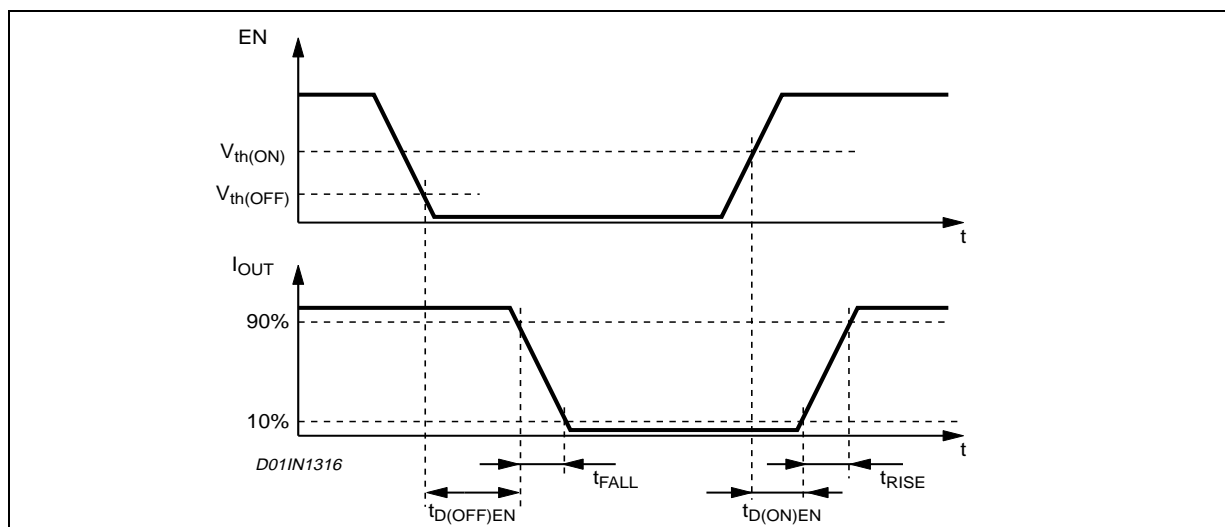
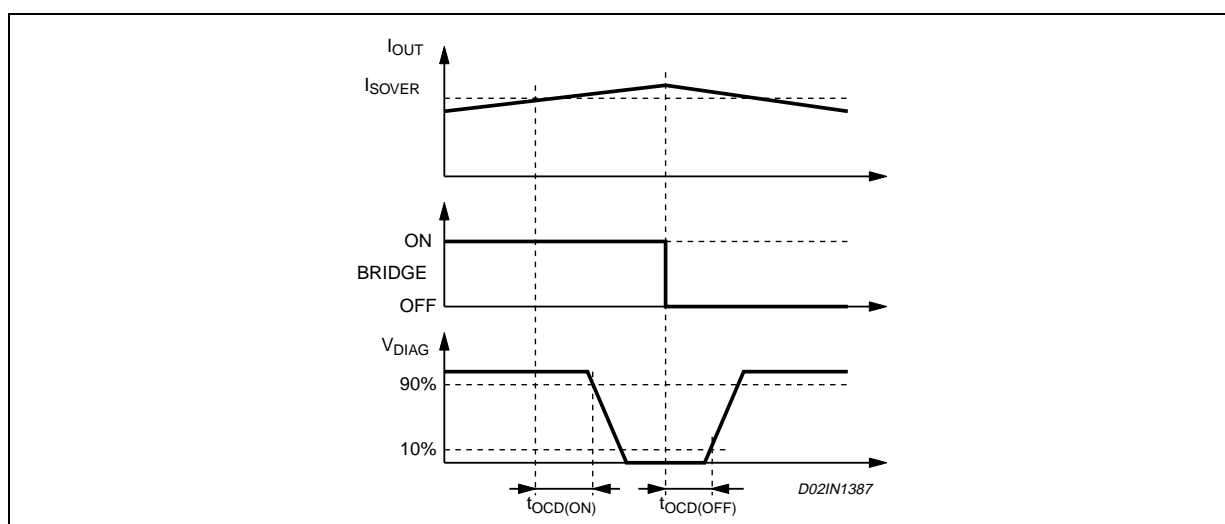


Figure 2. Overcurrent Detection Timing Definition



**CIRCUIT DESCRIPTION**

**POWER STAGES and CHARGE PUMP**

The L6235 integrates a Three-Phase Bridge, which consists of 6 Power MOSFETs connected as shown on the Block Diagram. Each Power MOS has an  $R_{DS(ON)} = 0.3\Omega$  (typical value @25°C) with intrinsic fast freewheeling diode. Switching patterns are generated by the PWM Current Controller and the Hall Effect Sensor Decoding Logic (see relative paragraphs). Cross conduction protection is implemented by using a dead time ( $t_{DT} = 1\mu s$  typical value) set by internal timing circuit between the turn off and turn on of two Power MOSFETs in one leg of a bridge.

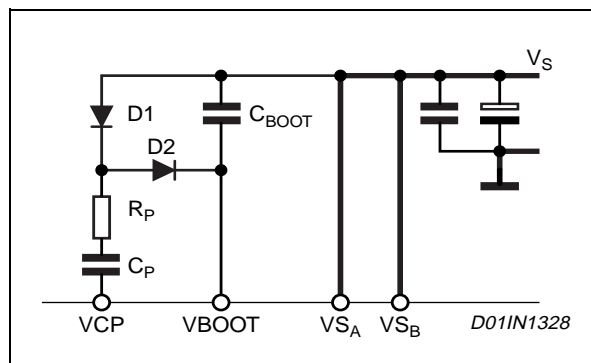
Pins  $VS_A$  and  $VS_B$  MUST be connected together to the supply voltage ( $V_S$ ).

Using N-Channel Power MOS for the upper transistors in the bridge requires a gate drive voltage above the power supply voltage. The Bootstrapped Supply ( $V_{BOOT}$ ) is obtained through an internal oscillator and few external components to realize a charge pump circuit as shown in Figure 3. The oscillator output (pin VCP) is a square wave at 600KHz (typically) with 10V amplitude. Recommended values/part numbers for the charge pump circuit are shown in Table1.

**Table 1. Charge Pump External Component Values.**

$C_{BOOT}$	220nF
$C_P$	10nF
$R_P$	100Ω
$D_1$	1N4148
$D_2$	1N4148

**Figure 3. Charge Pump Circuit**

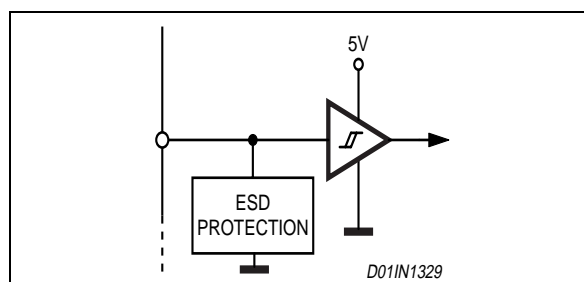


**LOGIC INPUTS**

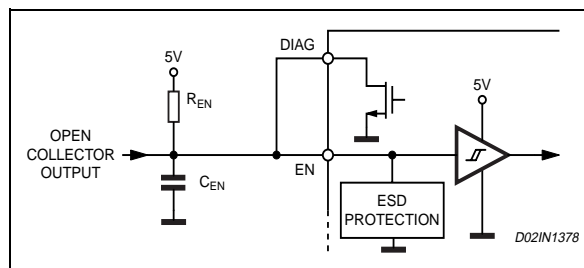
Pins FWD/REV, BRAKE, EN,  $H_1$ ,  $H_2$  and  $H_3$  are TTL/CMOS and  $\mu C$  compatible logic inputs. The internal structure is shown in Figure 4. Typical value for turn-ON and turn-OFF thresholds are respectively  $V_{th(ON)} = 1.8V$  and  $V_{th(OFF)} = 1.3V$ .

Pin EN (enable) may be used to implement Overcurrent and Thermal protection by connecting it to the open collector DIAG output. If the protection and an external disable function are both desired, the appropriate connection must be implemented. When the external signal is from an open collector output, the circuit in Figure 5 can be used. For external circuits that are push pull outputs the circuit in Figure 6 could be used. The resistor  $R_{EN}$  should be chosen in the range from 2.2KΩ to 180KΩ. Recommended values for  $R_{EN}$  and  $C_{EN}$  are respectively 100KΩ and 5.6nF. More information for selecting the values can be found in the Overcurrent Protection section.

**Figure 4. Logic Input Internal Structure**



**Figure 5. Pin EN Open Collector Driving**



**Figure 6. Pin EN Push-Pull Driving**

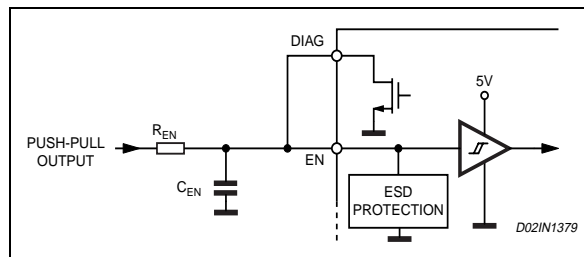






Figure 8. Output Current Regulation Waveforms

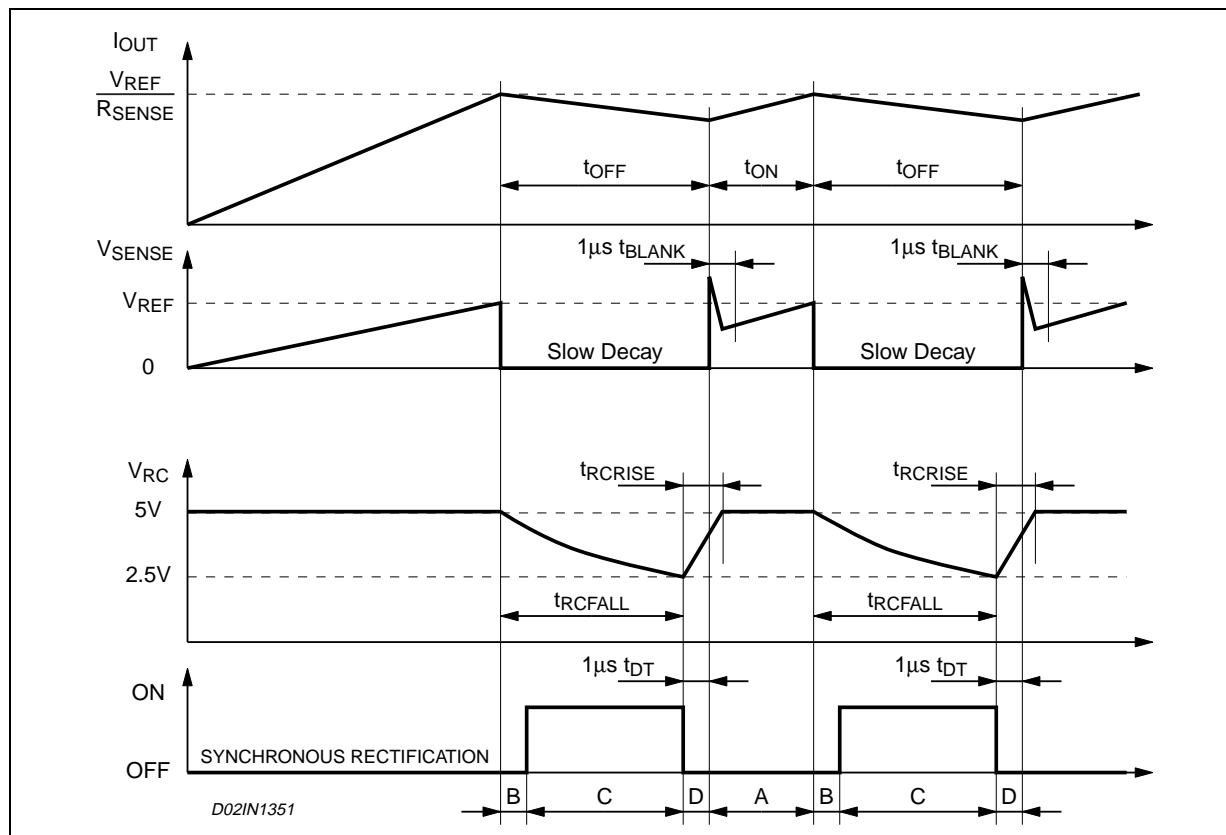


Figure 9 shows the magnitude of the Off Time  $t_{OFF}$  versus  $C_{OFF}$  and  $R_{OFF}$  values. It can be approximately calculated from the equations:

$$t_{RCFALL} = 0.6 \cdot R_{OFF} \cdot C_{OFF}$$

$$t_{OFF} = t_{RCFALL} + t_{DT} = 0.6 \cdot R_{OFF} \cdot C_{OFF} + t_{DT}$$

where  $R_{OFF}$  and  $C_{OFF}$  are the external component values and  $t_{DT}$  is the internally generated Dead Time with:

$$20K\Omega \leq R_{OFF} \leq 100K\Omega$$

$$0.47nF \leq C_{OFF} \leq 100nF$$

$$t_{DT} = 1\mu s \text{ (typical value)}$$

Therefore:

$$t_{OFF(MIN)} = 6.6\mu s$$

$$t_{OFF(MAX)} = 6ms$$

These values allow a sufficient range of  $t_{OFF}$  to implement the drive circuit for most motors.

The capacitor value chosen for  $C_{OFF}$  also affects the Rise Time  $t_{RCRISE}$  of the voltage at the pin  $R_{COFF}$ . The Rise Time  $t_{RCRISE}$  will only be an issue if the capacitor is not completely charged before the next time the monostable is triggered. Therefore, the On Time  $t_{ON}$ , which depends by motors and supply parameters, has to be bigger than  $t_{RCRISE}$  for allowing a good current regulation by the PWM stage. Furthermore, the On Time  $t_{ON}$  can not be smaller than the minimum on time  $t_{ON(MIN)}$ .

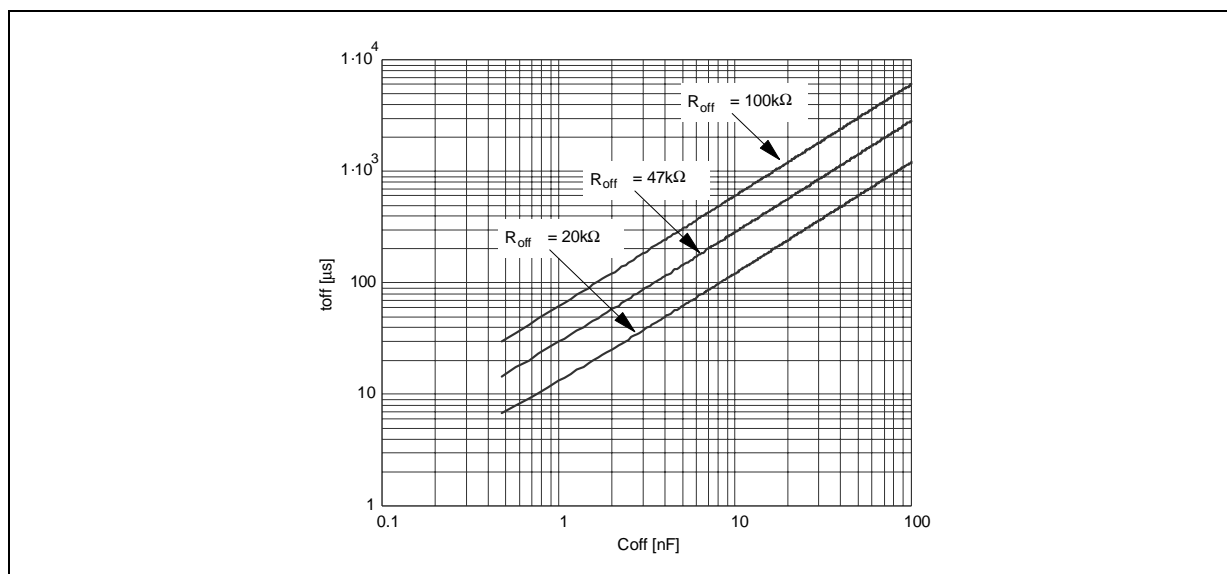
$$\begin{cases} t_{ON} > t_{ON(MIN)} = 1.5\mu s \text{ (typ. value)} \\ t_{ON} > t_{RCRISE} - t_{DT} \end{cases}$$

$$t_{RCRISE} = 600 \cdot C_{OFF}$$

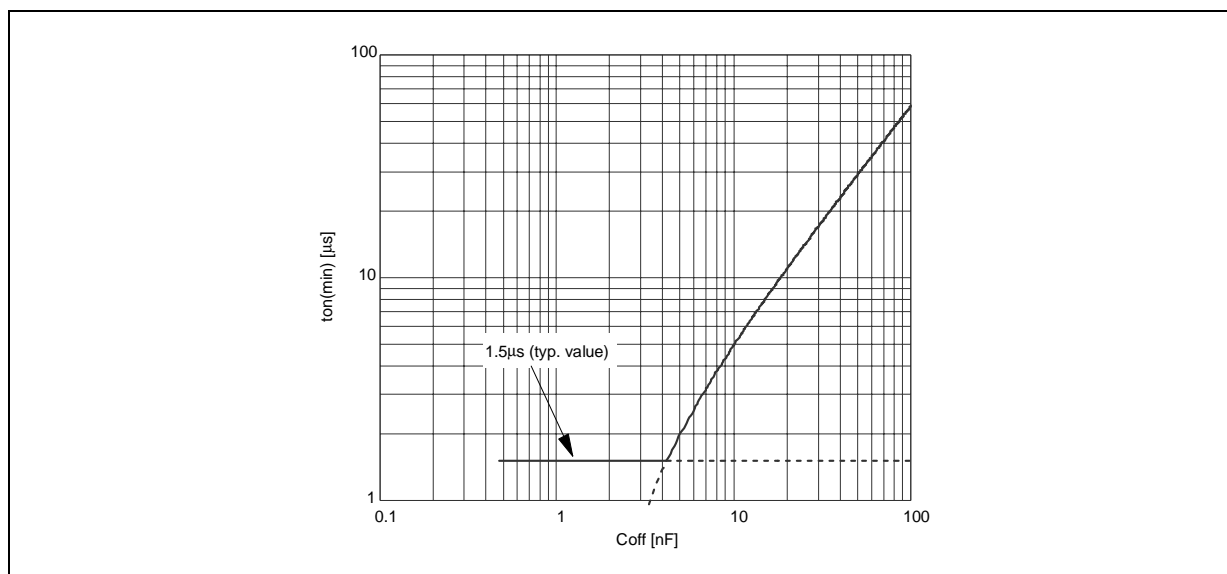
Figure 10 shows the lower limit for the On Time  $t_{ON}$  for having a good PWM current regulation capacity. It has to be said that  $t_{ON}$  is always bigger than  $t_{ON(MIN)}$  because the device imposes this condition, but it can be smaller than  $t_{RCRISE} - t_{DT}$ . In this last case the device continues to work but the Off Time  $t_{OFF}$  is not more constant.

So, small  $C_{OFF}$  value gives more flexibility for the applications (allows smaller On Time and, therefore, higher switching frequency), but, the smaller is the value for  $C_{OFF}$ , the more influential will be the noises on the circuit performance.

**Figure 9.  $t_{OFF}$  versus  $C_{OFF}$  and  $R_{OFF}$ .**



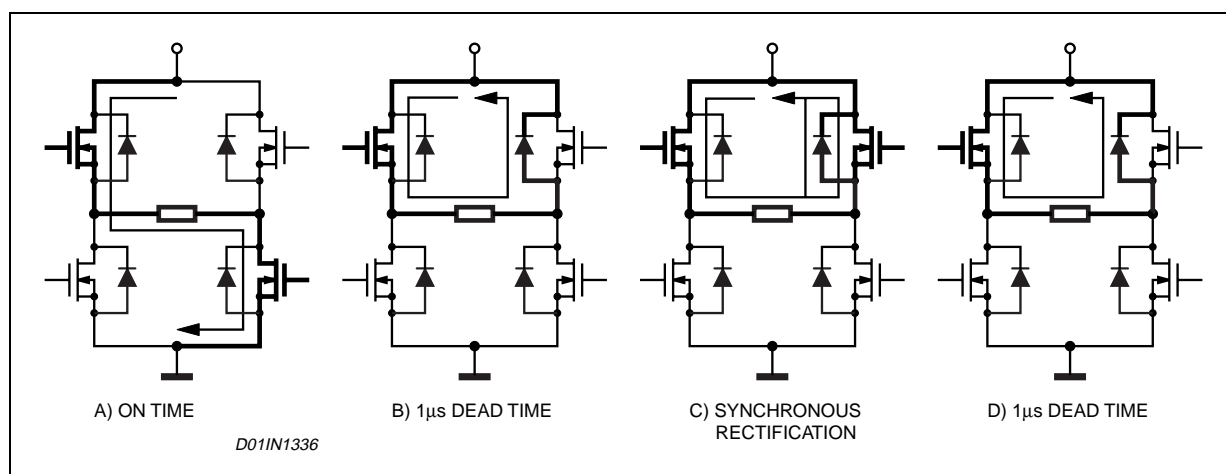
**Figure 10. Area where  $t_{ON}$  can vary maintaining the PWM regulation.**



### SLOW DECAY MODE

Figure 11 shows the operation of the bridge in the Slow Decay mode during the Off Time. At any time only two legs of the three-phase bridge are active, therefore only the two active legs of the bridge are shown in the figure and the third leg will be off. At the start of the Off Time, the lower power MOS is switched off and the current recirculates around the upper half of the bridge. Since the voltage across the coil is low, the current decays slowly. After the Dead Time the upper power MOS is operated in the synchronous rectification mode reducing the impedance of the freewheeling diode and the related conducting losses. When the monostable times out, upper MOS that was operating the synchronous mode turns off and the lower power MOS is turned on again after some delay set by the Dead Time to prevent cross conduction.

Figure 11. Slow Decay Mode Output Stage Configurations



### DECODING LOGIC

The Decoding Logic section is a combinatory logic that provides the appropriate driving of the three-phase bridge outputs according to the signals coming from the three Hall Sensors that detect rotor position in a 3-phase BLDC motor. This novel combinatory logic discriminates between the actual sensor positions for sensors spaced at 60, 120, 240 and 300 electrical degrees. This decoding method allows the implementation of a universal IC without dedicating pins to select the sensor configuration.

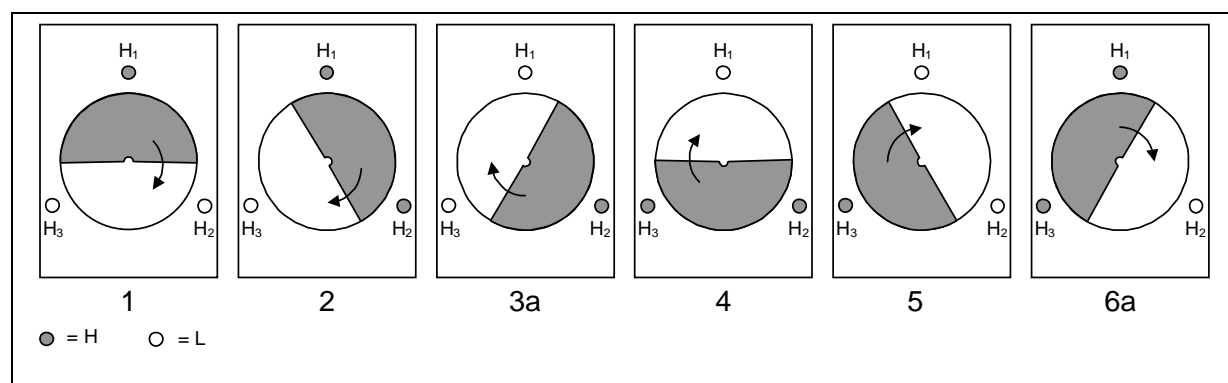
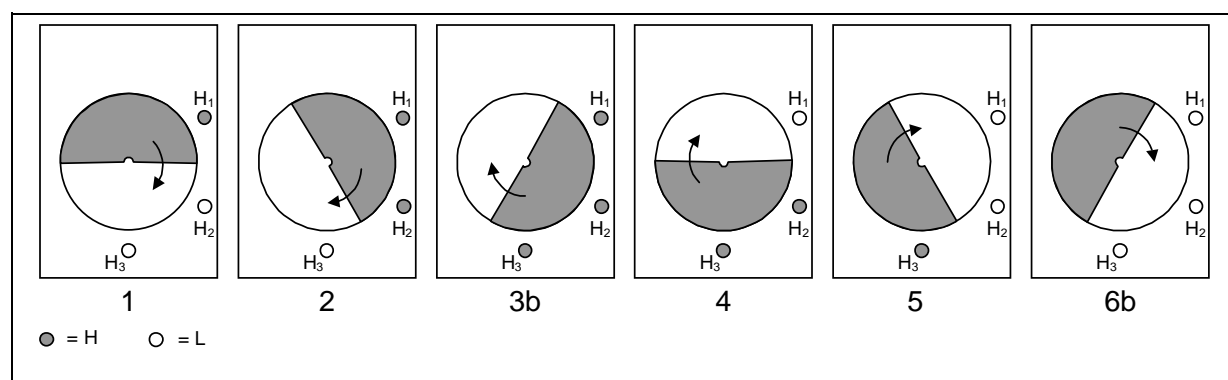
There are eight possible input combinations for three sensor inputs. Six combinations are valid for rotor positions with 120 electrical degrees sensor phasing (see Figure 12, positions 1, 2, 3a, 4, 5 and 6a) and six combinations are valid for rotor positions with 60 electrical degrees phasing (see Figure 14, positions 1, 2, 3b, 4, 5 and 6b). Four of them are in common (1, 2, 4 and 5) whereas there are two combinations used only in 120 electrical degrees sensor phasing (3a and 6a) and two combinations used only in 60 electrical degrees sensor phasing (3b and 6b).

The decoder can drive motors with different sensor configuration simply by following the Table 2. For any input configuration ( $H_1$ ,  $H_2$  and  $H_3$ ) there is one output configuration ( $OUT_1$ ,  $OUT_2$  and  $OUT_3$ ). The output configuration 3a is the same than 3b and analogously output configuration 6a is the same than 6b.

The sequence of the Hall codes for 300 electrical degrees phasing is the reverse of 60 and the sequence of the Hall codes for 240 phasing is the reverse of 120. So, by decoding the 60 and the 120 codes it is possible to drive the motor with all the four conventions by changing the direction set.

**Table 2. 60 and 120 Electrical Degree Decoding Logic in Forward Direction.**

Hall 120°	1	2	3a	-	4	5	6a	-
Hall 60°	1	2	-	3b	4	5	-	6b
H <sub>1</sub>	H	H	L	H	L	L	H	L
H <sub>2</sub>	L	H	H	H	H	L	L	L
H <sub>3</sub>	L	L	L	H	H	H	H	L
OUT <sub>1</sub>	Vs	High Z	GND	GND	GND	High Z	Vs	Vs
OUT <sub>2</sub>	High Z	Vs	Vs	Vs	High Z	GND	GND	GND
OUT <sub>3</sub>	GND	GND	High Z	High Z	Vs	Vs	High Z	High Z
Phasing	1->3	2->3	2->1	2->1	3->1	3->2	1->2	1->2

**Figure 12. 120° Hall Sensor Sequence.****Figure 13. 60° Hall Sensor Sequence.**

## TACHO

A tachometer function consists of a monostable, with constant off time ( $t_{PULSE}$ ), whose input is one Hall Effect signal ( $H_1$ ). It allows developing an easy speed control loop by using an external op amp, as shown in Figure 14. For component values refer to Application Information section.

The monostable output drives an open drain output pin (TACHO). At each rising edge of the Hall Effect Sensors  $H_1$ , the monostable is triggered and the MOSFET connected to pin TACHO is turned off for a constant time  $t_{PULSE}$  (see Figure 15). The off time  $t_{PULSE}$  can be set using the external RC network ( $R_{PUL}$ ,  $C_{PUL}$ ) connected to the pin RCPULSE. Figure 16 gives the relation between  $t_{PULSE}$  and  $C_{PUL}$ ,  $R_{PUL}$ . We have approximately:

$$t_{PULSE} = 0.6 \cdot R_{PUL} \cdot C_{PUL}$$

where  $C_{PUL}$  should be chosen in the range 1nF ... 100nF and  $R_{PUL}$  in the range 20K $\Omega$  ... 100K $\Omega$ .

By connecting the tachometer pin to an external pull-up resistor, the output signal average value  $V_M$  is proportional to the frequency of the Hall Effect signal and, therefore, to the motor speed. This realizes a simple Frequency-to-Voltage Converter. An op amp, configured as an integrator, filters the signal and compares it with a reference voltage  $V_{REF}$ , which sets the speed of the motor.

$$V_M = \frac{t_{PULSE}}{T} \cdot V_{DD}$$

**Figure 14. Tacho Operation Waveforms.**

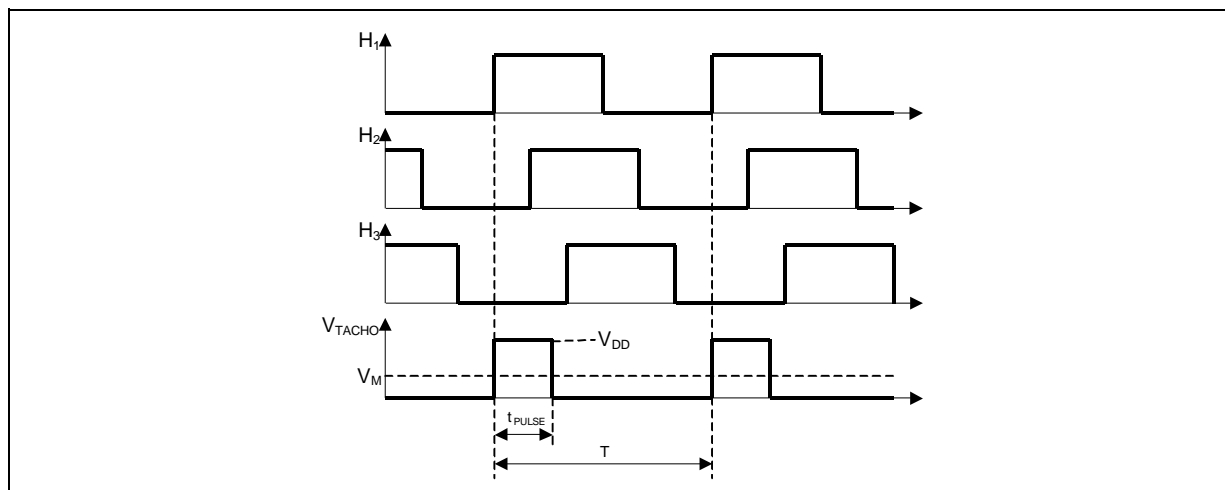


Figure 15. Tachometer Speed Control Loop.

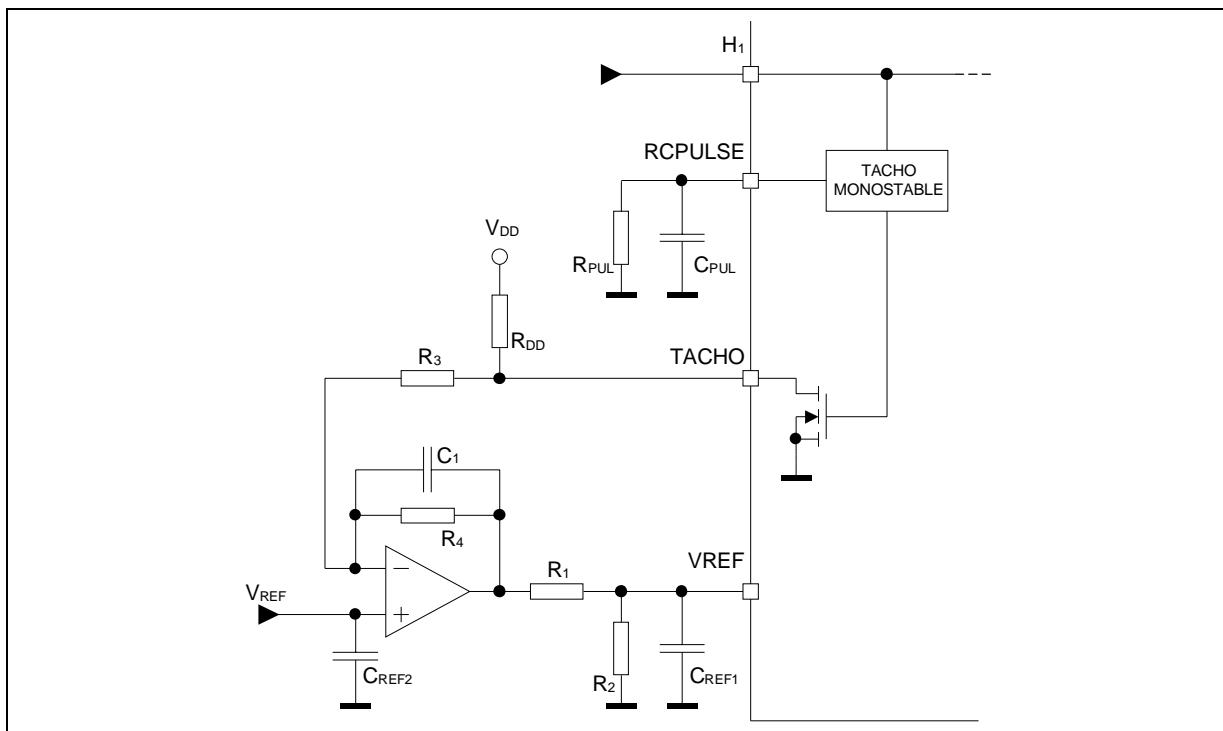
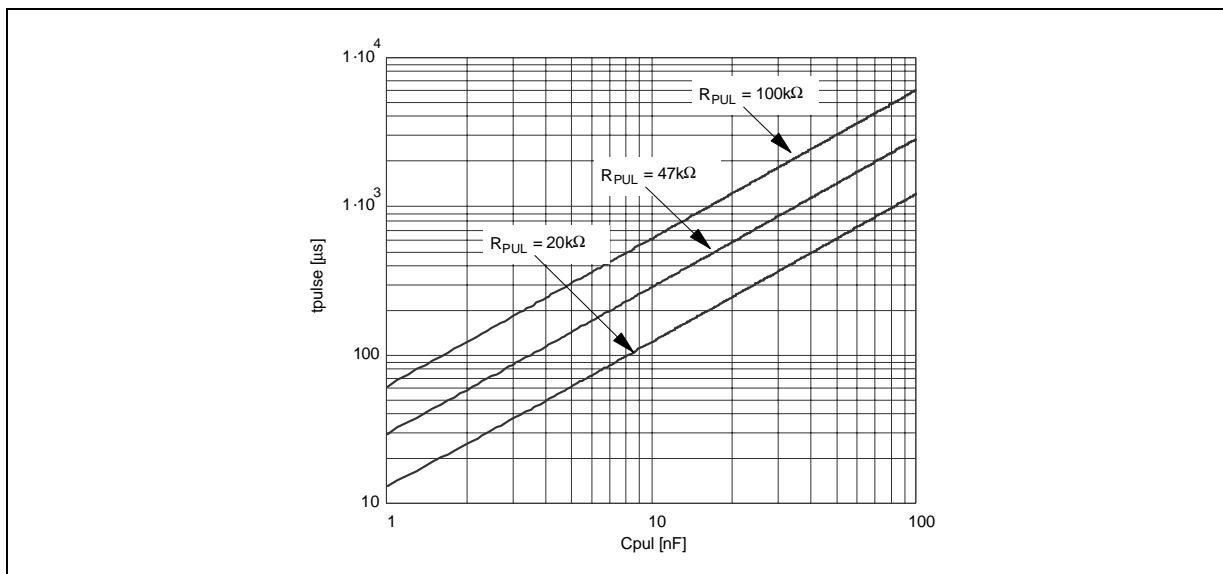


Figure 16.  $t_{PULSE}$  versus  $C_{PUL}$  and  $R_{PUL}$ .



### NON-DISSIPATIVE OVERCURRENT DETECTION and PROTECTION

The L6235 integrates an Overcurrent Detection Circuit (OCD) for full protection. This circuit provides Output-to-Output and Output-to-Ground short circuit protection as well. With this internal over current detection, the external current sense resistor normally used and its associated power dissipation are eliminated. Figure 17 shows a simplified schematic for the overcurrent detection circuit.

To implement the over current detection, a sensing element that delivers a small but precise fraction of the output current is implemented with each High Side power MOS. Since this current is a small fraction of the output current there is very little additional power dissipation. This current is compared with an internal reference current  $I_{REF}$ . When the output current reaches the detection threshold (typically  $I_{SOVER} = 5.6A$ ) the OCD comparator signals a fault condition. When a fault condition is detected, an internal open drain MOS with a pull down capability of 4mA connected to pin DIAG is turned on.

The pin DIAG can be used to signal the fault condition to a  $\mu C$  or to shut down the Three-Phase Bridge simply by connecting it to pin EN and adding an external R-C (see  $R_{EN}$ ,  $C_{EN}$ ).

**Figure 17. Overcurrent Protection Simplified Schematic**

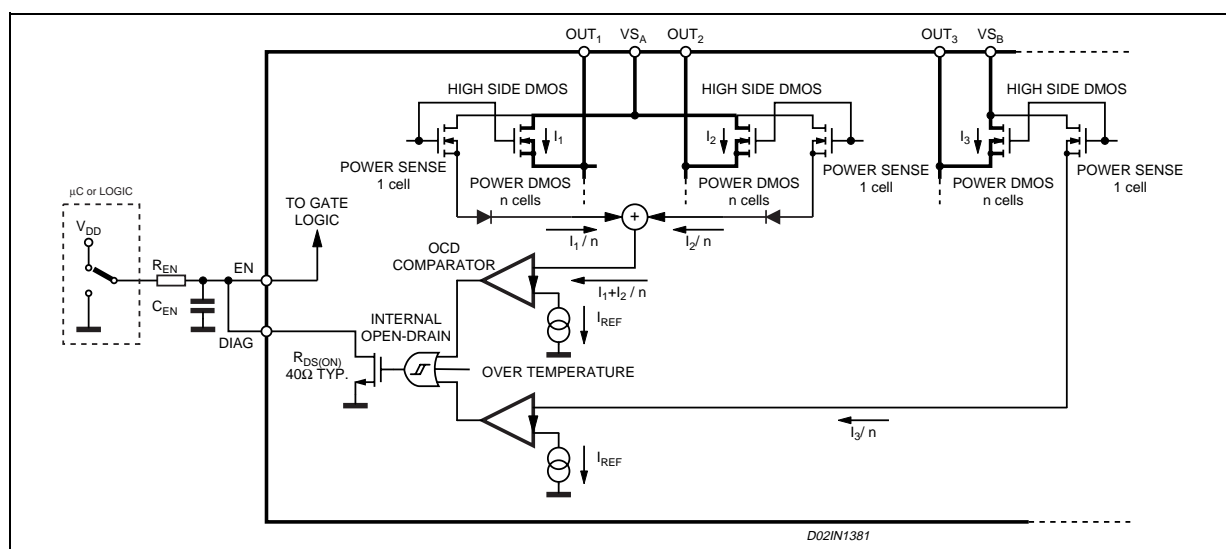


Figure 18 shows the Overcurrent Detection operation. The Disable Time  $t_{DISABLE}$  before recovering normal operation can be easily programmed by means of the accurate thresholds of the logic inputs. It is affected whether by  $C_{EN}$  and  $R_{EN}$  values and its magnitude is reported in Figure 19. The Delay Time  $t_{DELAY}$  before turning off the bridge when an overcurrent has been detected depends only by  $C_{EN}$  value. Its magnitude is reported in Figure 20.

$C_{EN}$  is also used for providing immunity to pin EN against fast transient noises. Therefore the value of  $C_{EN}$  should be chosen as big as possible according to the maximum tolerable Delay Time and the  $R_{EN}$  value should be chosen according to the desired Disable Time.

The resistor  $R_{EN}$  should be chosen in the range from 2.2K $\Omega$  to 180K $\Omega$ . Recommended values for  $R_{EN}$  and  $C_{EN}$  are respectively 100K $\Omega$  and 5.6nF that allow obtaining 200 $\mu s$  Disable Time.



Figure 18. Overcurrent Protection Waveforms

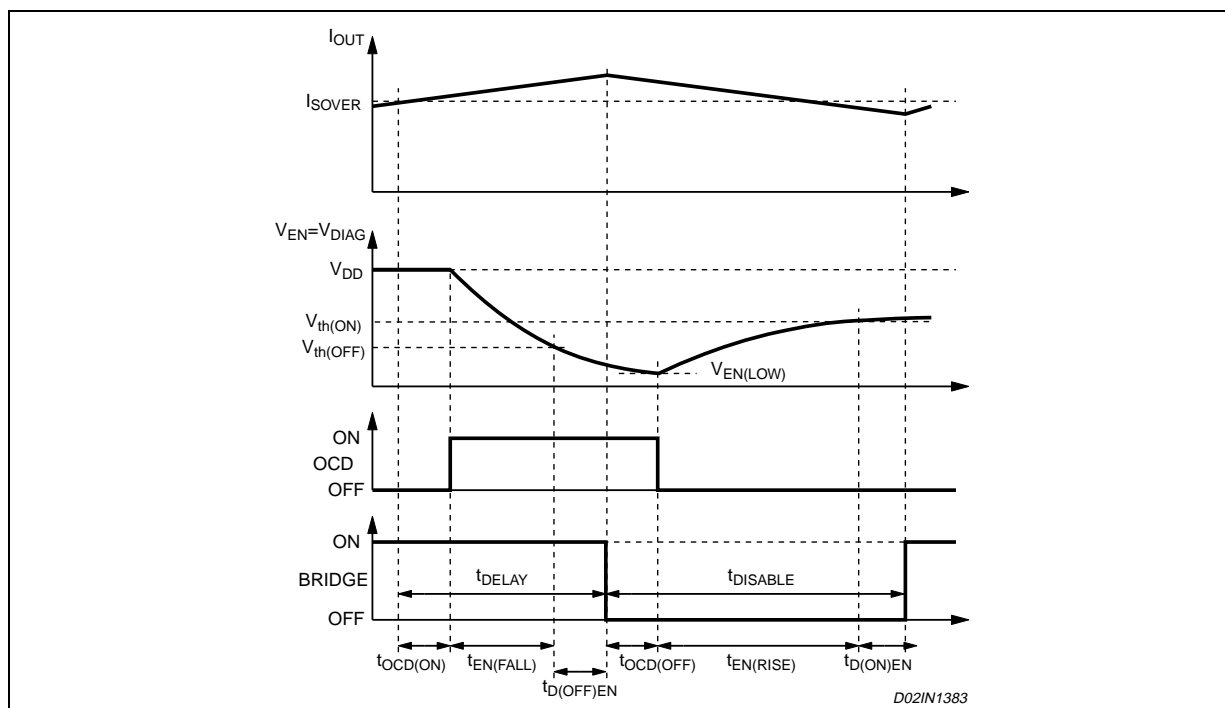


Figure 19.  $t_{DISABLE}$  versus  $C_{EN}$  and  $R_{EN}$ .

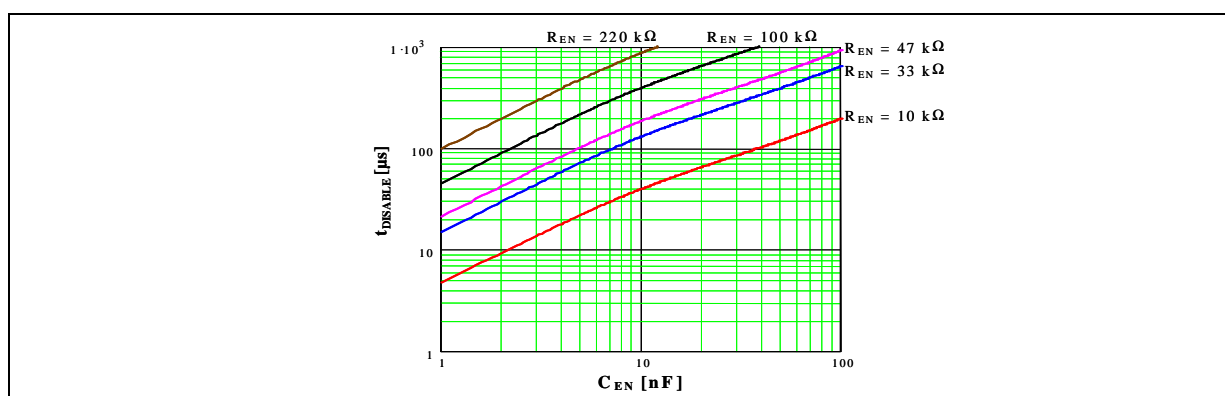
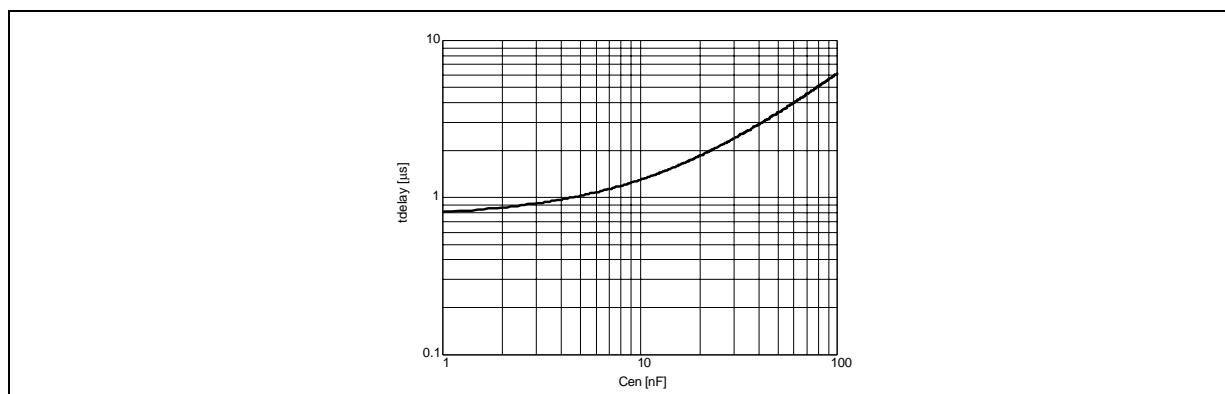


Figure 20.  $t_{DELAY}$  versus  $C_{EN}$ .



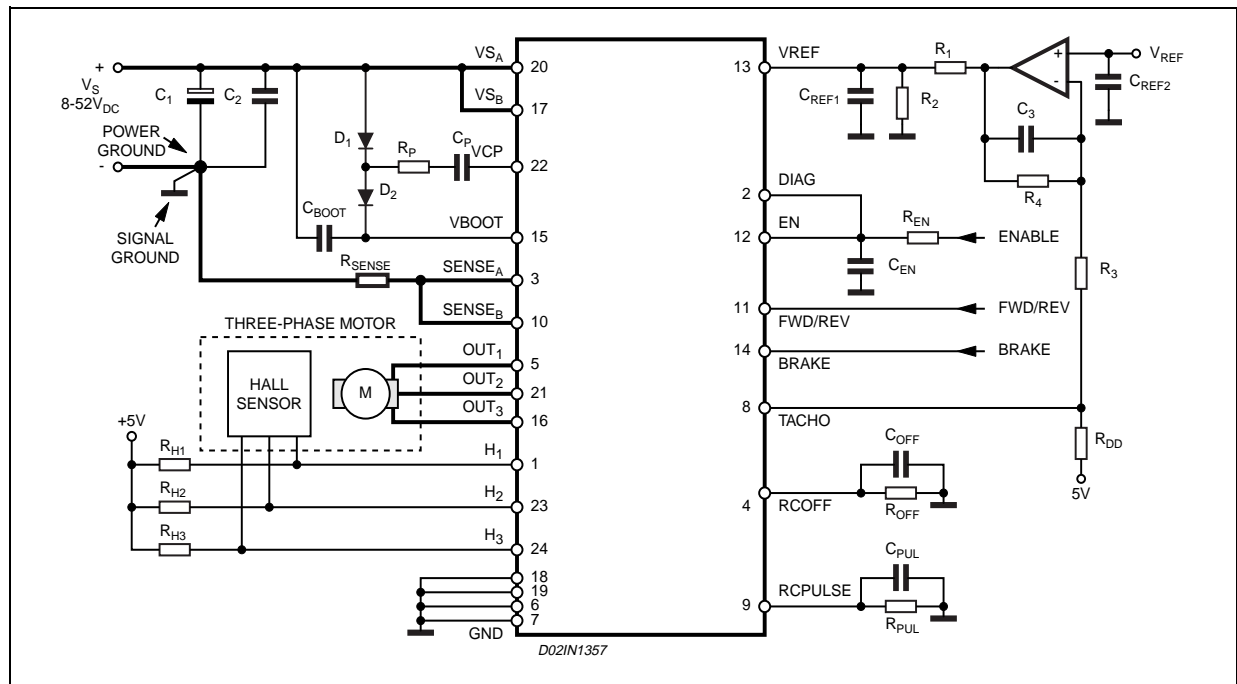
**APPLICATION INFORMATION**

A typical application using L6235 is shown in Figure 21. Typical component values for the application are shown in Table 3. A high quality ceramic capacitor ( $C_2$ ) in the range of 100nF to 200nF should be placed between the power pins  $VS_A$  and  $VS_B$  and ground near the L6235 to improve the high frequency filtering on the power supply and reduce high frequency transients generated by the switching. The capacitor ( $C_{EN}$ ) connected from the EN input to ground sets the shut down time when an over current is detected (see Overcurrent Protection). The two current sensing inputs ( $SENSE_A$  and  $SENSE_B$ ) should be connected to the sensing resistor  $R_{SENSE}$  with a trace length as short as possible in the layout. The sense resistor should be non-inductive resistor to minimize the di/dt transients across the resistor. To increase noise immunity, unused logic pins are best connected to 5V (High Logic Level) or GND (Low Logic Level) (see pin description). It is recommended to keep Power Ground and Signal Ground separated on PCB.

**Table 3. Component Values for Typical Application.**

$C_1$	100 $\mu$ F	$R_1$	5K6 $\Omega$
$C_2$	100nF	$R_2$	1K8 $\Omega$
$C_3$	220nF	$R_3$	4K7 $\Omega$
$C_{BOOT}$	220nF	$R_4$	1M $\Omega$
$C_{OFF}$	1nF	$R_{DD}$	1K $\Omega$
$C_{PUL}$	10nF	$R_{EN}$	100K $\Omega$
$C_{REF1}$	33nF	$R_P$	100 $\Omega$
$C_{REF2}$	100nF	$R_{SENSE}$	0.3 $\Omega$
$C_{EN}$	5.6nF	$R_{OFF}$	33K $\Omega$
$C_P$	10nF	$R_{PUL}$	47K $\Omega$
$D_1$	1N4148	$R_{H1}, R_{H2}, R_{H3}$	10K $\Omega$
$D_2$	1N4148		

**Figure 21. Typical Application**

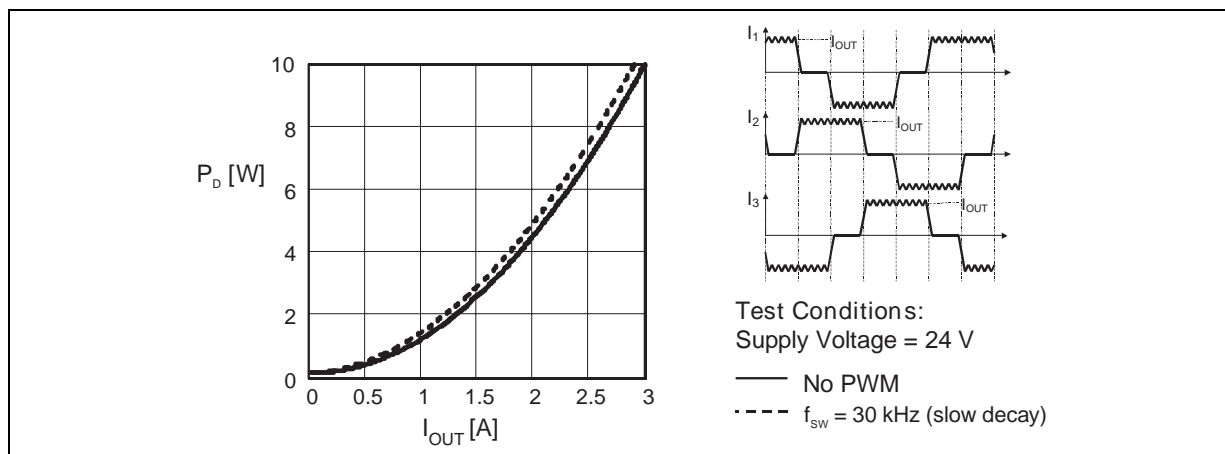


## OUTPUT CURRENT CAPABILITY AND IC POWER DISSIPATION

In Figure 22 is shown the approximate relation between the output current and the IC power dissipation using PWM current control.

For a given output current the power dissipated by the IC can be easily evaluated, in order to establish which package should be used and how large must be the on-board copper dissipating area to guarantee a safe operating junction temperature (125°C maximum).

**Figure 22. IC Power Dissipation versus Output Power.**



## THERMAL MANAGEMENT

In most applications the power dissipation in the IC is the main factor that sets the maximum current that can be delivered by the device in a safe operating condition. Selecting the appropriate package and heatsinking configuration for the application is required to maintain the IC within the allowed operating temperature range for the application. Figures 23, 24 and 25 show the Junction-to-Ambient Thermal Resistance values for the PowerSO36, PowerDIP24 and SO24 packages.

For instance, using a PowerSO package with copper slug soldered on a 1.5mm copper thickness FR4 board with 6cm<sup>2</sup> dissipating footprint (copper thickness of 35μm), the  $R_{th(j-amb)}$  is about 35°C/W. Figure 26 shows mounting methods for this package. Using a multi-layer board with vias to a ground plane, thermal impedance can be reduced down to 15°C/W.

**Figure 23. PowerSO36 Junction-Ambient thermal resistance versus on-board copper area.**

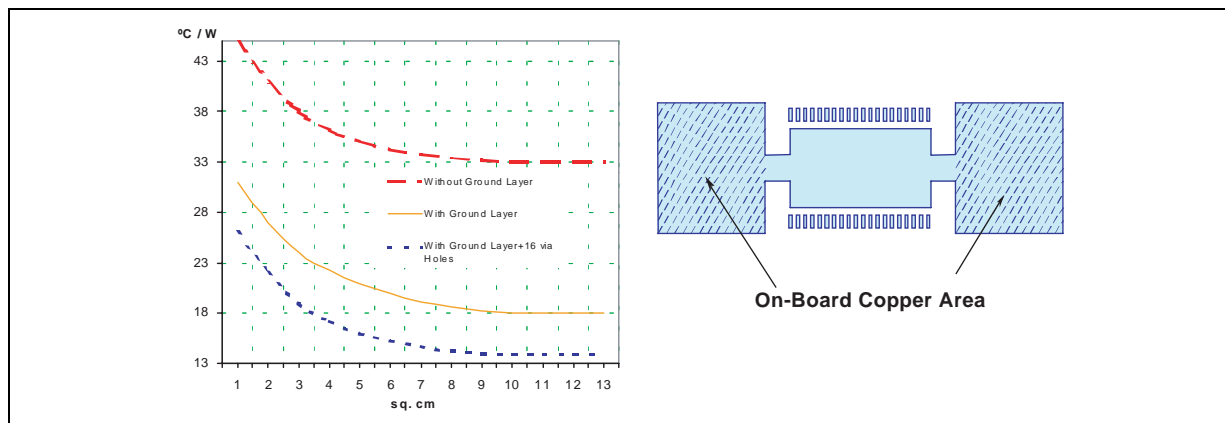


Figure 24. PowerDIP24 Junction-Ambient thermal resistance versus on-board copper area.

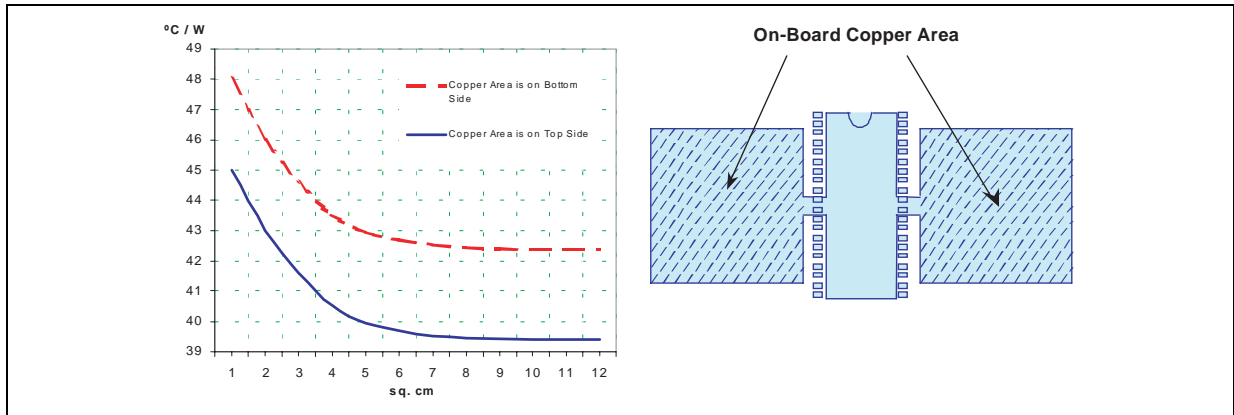


Figure 25. SO24 Junction-Ambient thermal resistance versus on-board copper area.

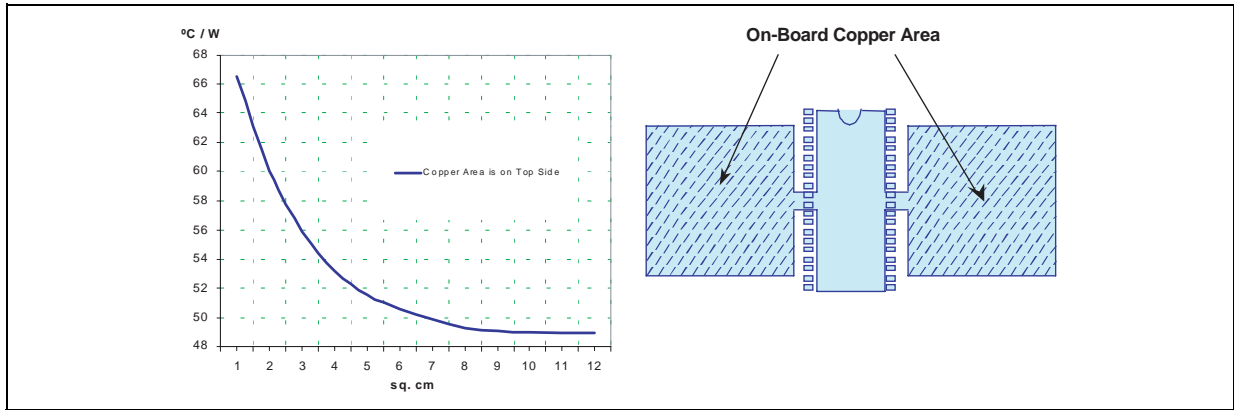
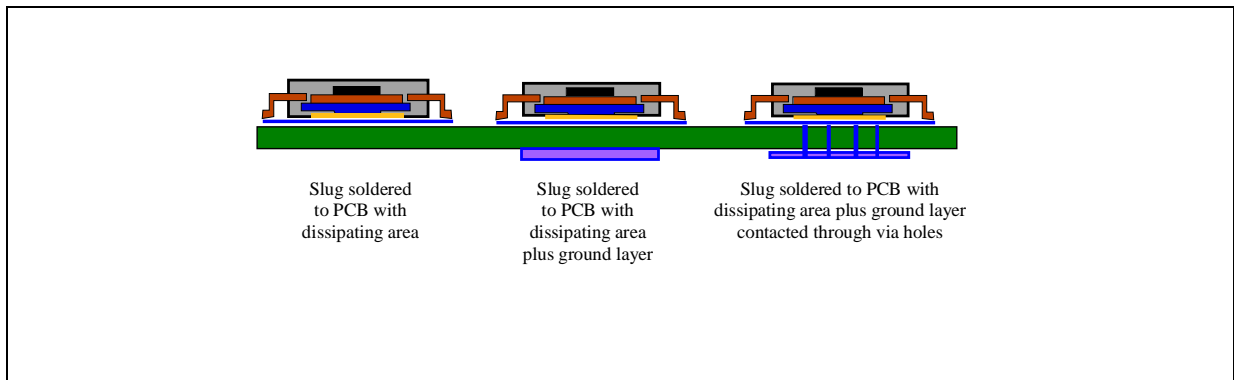
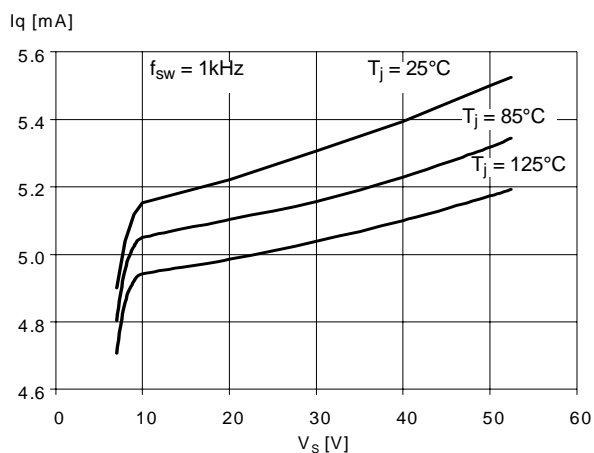


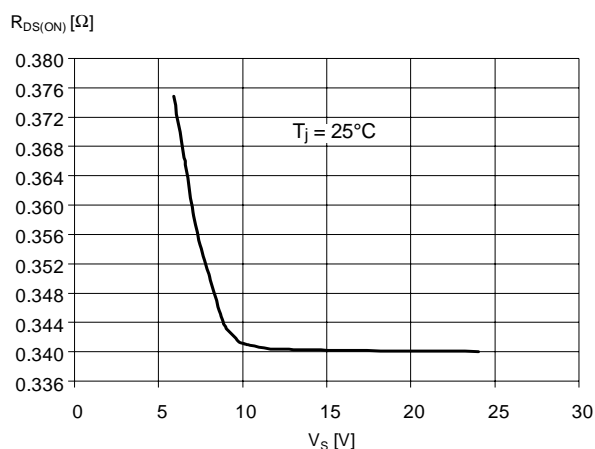
Figure 26. Mounting the PowerSO Package.



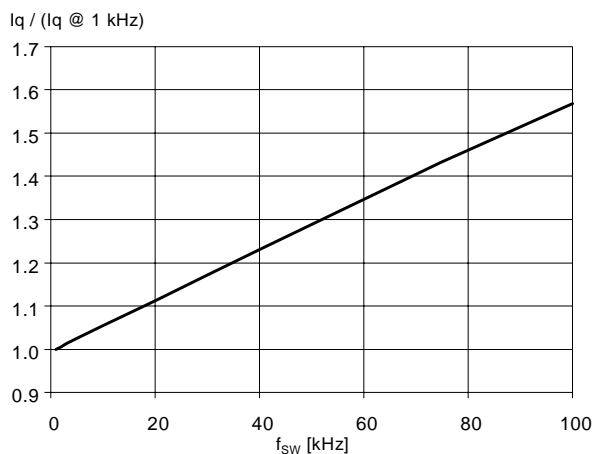
**Figure 27. Typical Quiescent Current vs. Supply Voltage**



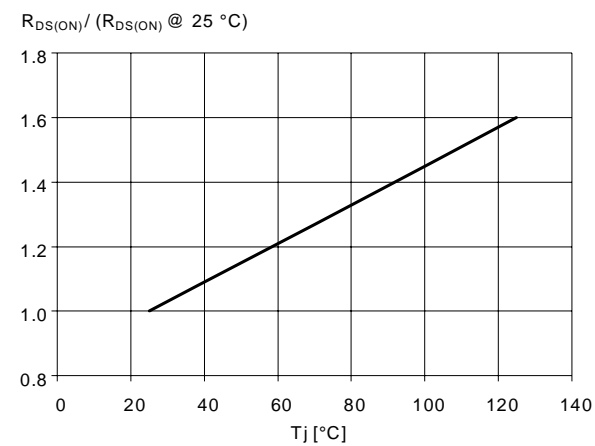
**Figure 30. Typical High-Side  $R_{DS(ON)}$  vs. Supply Voltage**



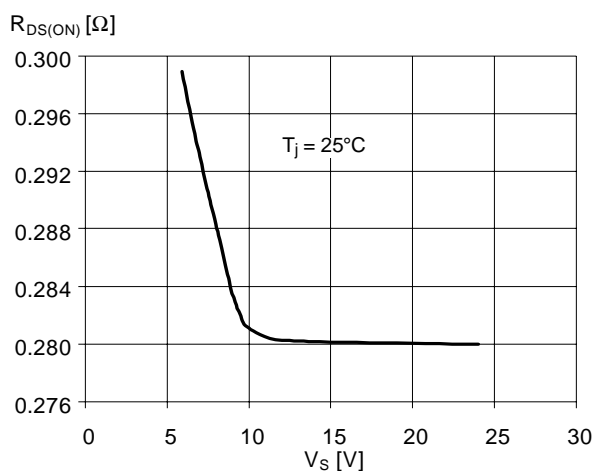
**Figure 28. Normalized Typical Quiescent Current vs. Switching Frequency**



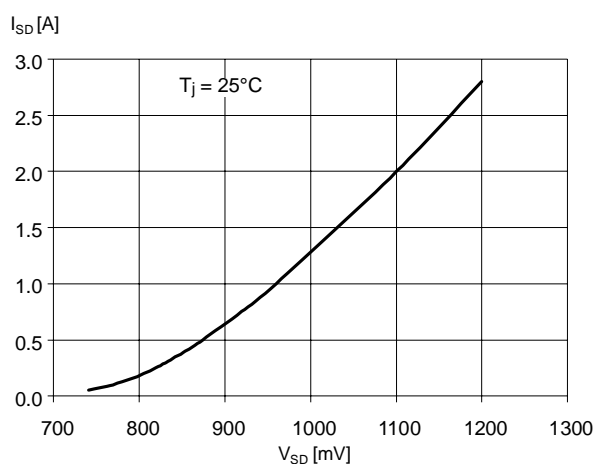
**Figure 31. Normalized  $R_{DS(ON)}$  vs. Junction Temperature (typical value)**



**Figure 29. Typical Low-Side  $R_{DS(ON)}$  vs. Supply Voltage**



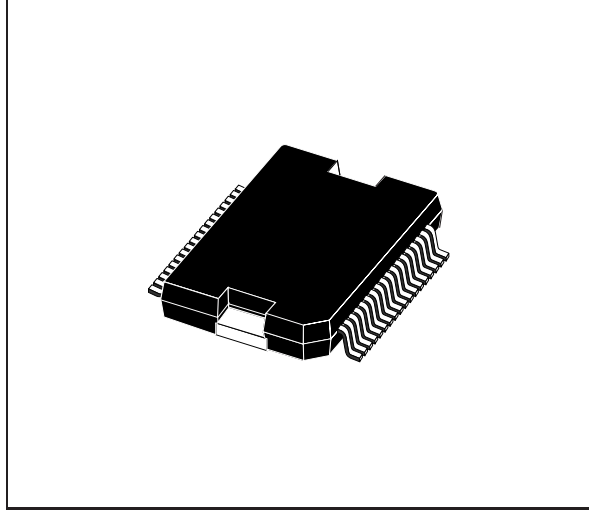
**Figure 32. Typical Drain-Source Diode Forward ON Characteristic**



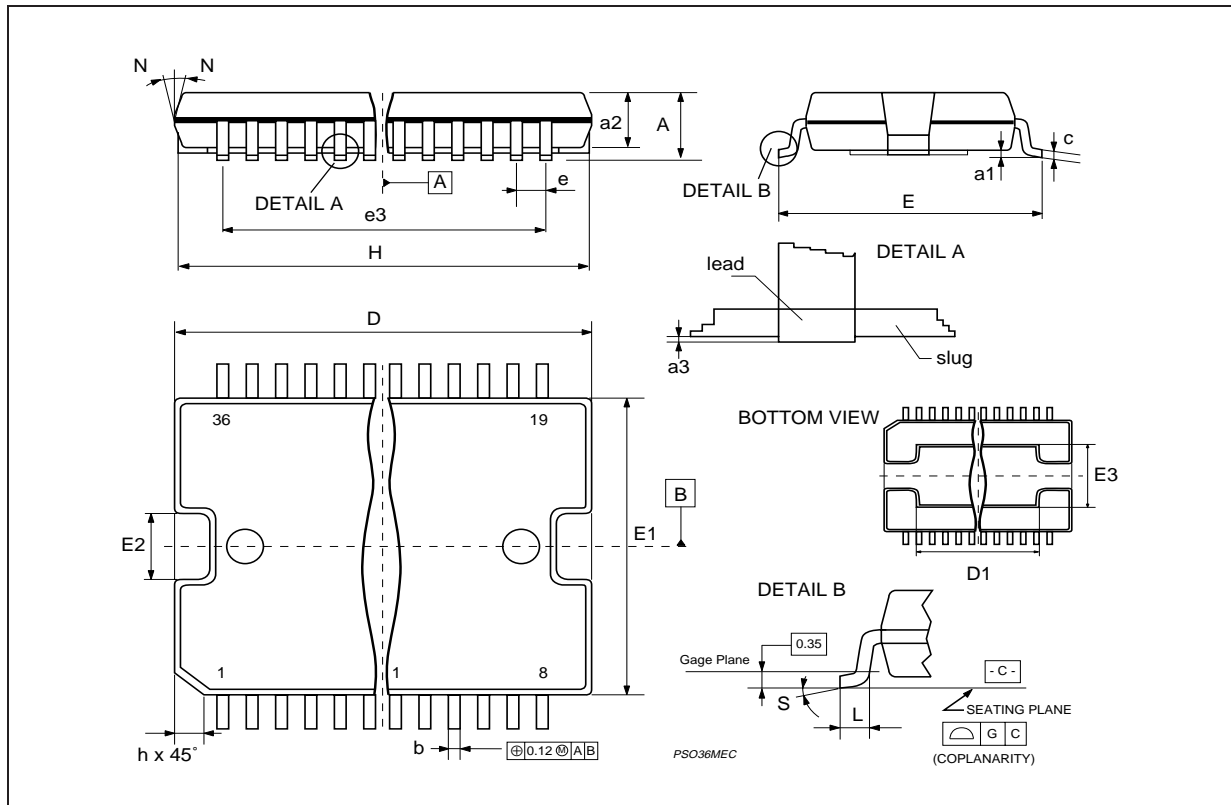
DIM.	mm			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A			3.60			0.141
a1	0.10		0.30	0.004		0.012
a2			3.30			0.130
a3	0		0.10	0		0.004
b	0.22		0.38	0.008		0.015
c	0.23		0.32	0.009		0.012
D (1)	15.80		16.00	0.622		0.630
D1	9.40		9.80	0.370		0.385
E	13.90		14.50	0.547		0.570
e		0.65			0.0256	
e3		11.05			0.435	
E1 (1)	10.90		11.10	0.429		0.437
E2			2.90			0.114
E3	5.80		6.20	0.228		0.244
E4	2.90		3.20	0.114		0.126
G	0		0.10	0		0.004
H	15.50		15.90	0.610		0.626
h			1.10			0.043
L	0.80		1.10	0.031		0.043
N	10°(max.)					
S	8°(max.)					

(1): "D" and "E1" do not include mold flash or protrusions  
 - Mold flash or protrusions shall not exceed 0.15mm (0.006 inch)  
 - Critical dimensions are "a3", "E" and "G".

## OUTLINE AND MECHANICAL DATA

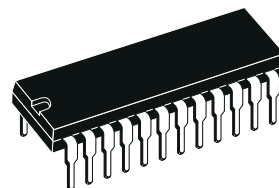


## PowerSO36

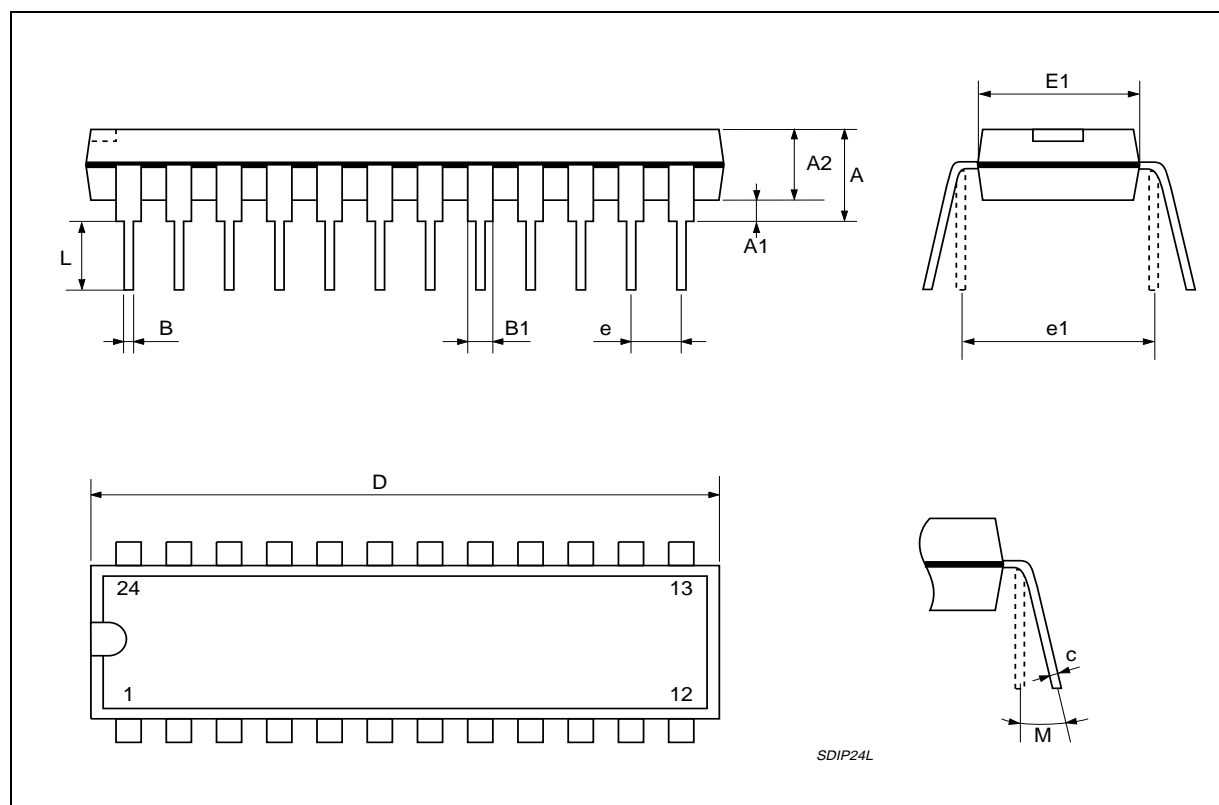


DIM.	mm			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A			4.320			0.170
A1	0.380			0.015		
A2		3.300			0.130	
B	0.410	0.460	0.510	0.016	0.018	0.020
B1	1.400	1.520	1.650	0.055	0.060	0.065
c	0.200	0.250	0.300	0.008	0.010	0.012
D	31.62	31.75	31.88	1.245	1.250	1.255
E	7.620		8.260	0.300		0.325
e		2.54			0.100	
E1	6.350	6.600	6.860	0.250	0.260	0.270
e1		7.620			0.300	
L	3.180		3.430	0.125		0.135
M	0° min, 15° max.					

## OUTLINE AND MECHANICAL DATA



**Powerdip 24**

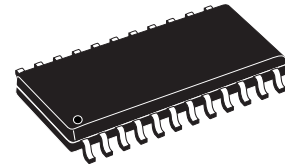


DIM.	mm			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A	2.35		2.65	0.093		0.104
A1	0.10		0.30	0.004		0.012
B	0.33		0.51	0.013		0.200
C	0.23		0.32	0.009		0.013
D (1)	15.20		15.60	0.598		0.614
E	7.40		7.60	0.291		0.299
e		1.27			0.050	
H	10.0		10.65	0.394		0.419
h	0.25		0.75	0.010		0.030
L	0.40		1.27	0.016		0.050
k	0° (min.), 8° (max.)					
ddd			0.10			0.004

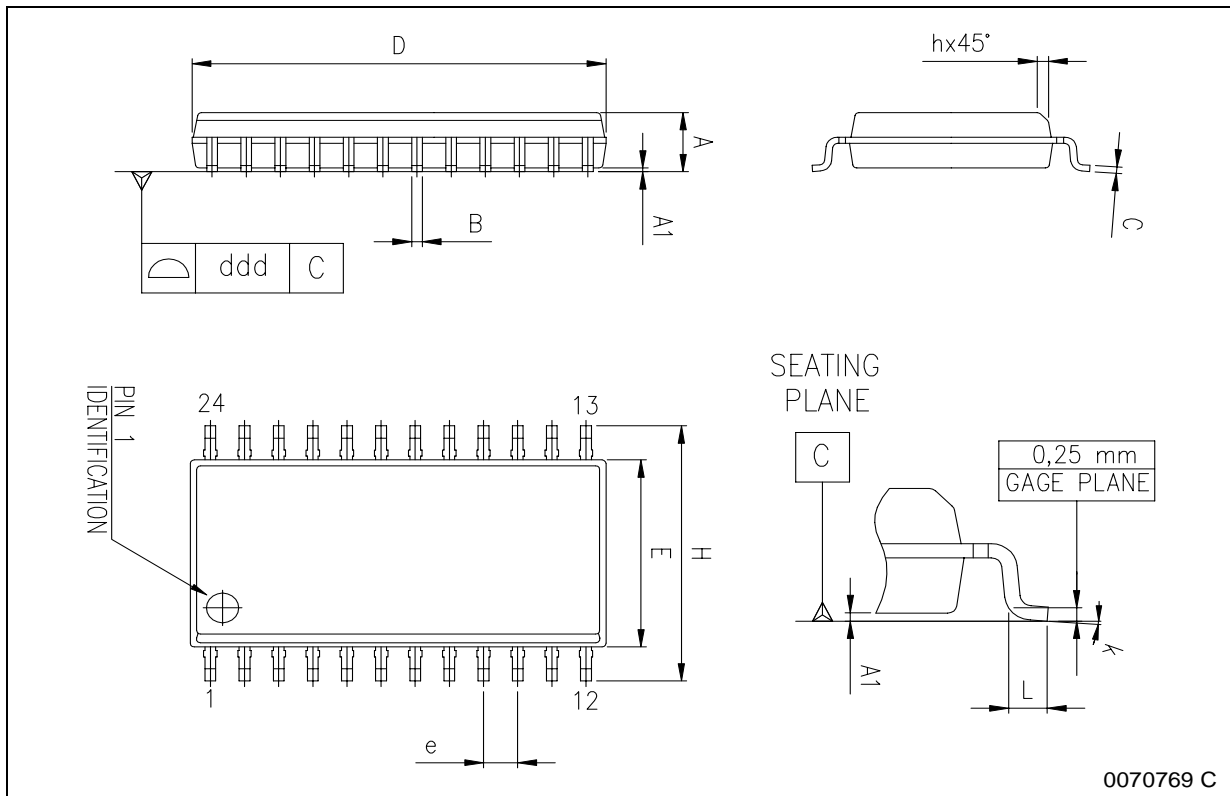
(1) "D" dimension does not include mold flash, protusions or gate burrs. Mold flash, protusions or gate burrs shall not exceed 0.15mm per side.

**OUTLINE AND MECHANICAL DATA**

Weight: 0.60gr



**SO24**





Information furnished is believed to be accurate and reliable. However, STMicroelectronics assumes no responsibility for the consequences of use of such information nor for any infringement of patents or other rights of third parties which may result from its use. No license is granted by implication or otherwise under any patent or patent rights of STMicroelectronics. Specifications mentioned in this publication are subject to change without notice. This publication supersedes and replaces all information previously supplied. STMicroelectronics products are not authorized for use as critical components in life support devices or systems without express written approval of STMicroelectronics.

The ST logo is a registered trademark of STMicroelectronics.  
All other names are the property of their respective owners

© 2003 STMicroelectronics - All rights reserved

**STMicroelectronics GROUP OF COMPANIES**

Australia - Belgium - Brazil - Canada - China - Czech Republic - Finland - France - Germany - Hong Kong - India - Israel - Italy - Japan -  
Malaysia - Malta - Morocco - Singapore - Spain - Sweden - Switzerland - United Kingdom - United States

[www.st.com](http://www.st.com)

